

Title (en)
HEAT-DISSIPATING ARRANGEMENT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)
WÄRME ABLEITENDE ANORDNUNG UND VERFAHREN ZUR HERSTELLUNG

Title (fr)
ENSEMBLE DISSIPATEUR DE CHALEUR ET PROCÉDÉ DE FABRICATION

Publication
EP 3527053 A1 20190821 (DE)

Application
EP 17772367 A 20170919

Priority
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• EP 2017073646 W 20170919

Abstract (en)
[origin: WO2018072951A1] Disclosed is a heat-dissipating arrangement having, wherein the heat-dissipating arrangement has at least one power module which has a printed circuit board (2) having components (3) to be cooled arranged thereon, and at least one heat sink (1) arranged on the printed circuit board (2) and over the components (3) to be cooled. On at least one of the components (3) to be cooled there is at least one heat-conducting element (100) which has a predefined structure extending from the printed circuit board (2) away from the printed circuit board into the heat sink (1), the heat-conducting element (100) containing a heat-dissipating medium in the interior thereof.

IPC 8 full level
H05K 7/20 (2006.01); **F28D 15/02** (2006.01)

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Citation (search report)
See references of WO 2018072951A1

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